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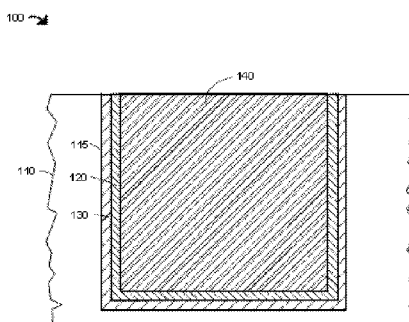


FIG. 1

(57) Abstract: Presented is a solution to activate an oxide surface for electroless deposition of a metal. The solution comprises a binding agent having at least one functional group capable of forming a chemical bond with the oxide surface and at least one functional group capable of forming a chemical bond with a catalyst. Also present are methods of fabricating electronic devices and electronic devices fabricated using the method.